

Abstract

The invention relates to a pressure transfer disk for transfer of a bonding pressure, especially in thermocompression bonding, from a pressurization apparatus to a wafer with the following:

- a first pressure side for making contact with the pressurization apparatus,
- a second pressure side facing away from the first pressure side with an effective contact area for making contact with the wafer and pressurizing it, at least the effective contact area having a low adhesiveness relative to the wafer.

Furthermore the invention relates to an application of the pressure transfer disk during bonding.

Figure 1 in this respect